

Thermal Bubble Type Angular Accelerometer

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Abstract

An RFID, Bluetooth as well as zigbee based thermal bubble type angular accelerometer includes a flexible substrate, a base layer, at least one cavity, and at least one sensing assembly. The base layer is formed on the flexible substrate. The at least one cavity is formed on the base layer. The at least one sensing assembly is suspended over the at least one cavity. The sensing assembly comprises a heater and two temperature sensing elements, wherein the two temperature sensing elements are substantially symmetrically disposed on opposite sides of the heater, and the heaters and the two temperature sensing elements extend in a radial direction.

Keyword : Thermal Bubble Type, Angular Accelerometer